

L Number	Hits	Search Text	DB	Time stamp
1	4	((("5170009") or ("6245259"))).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/21 13:13
-	3	coat\$4 with (chip IC die LED) and (amorphous adj fluororesin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/14 13:33
-	71	amorphous adj fluororesin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/14 13:33
-	6	(amorphous adj fluororesin) and (chip IC die LED)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/14 13:34
-	71	257/290-294.ccls. and (chip die IC LED) and coat\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/16 15:39
-	61	257/294.ccls. and (chip die IC LED)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/14 13:40
-	354	257/290-292.ccls. and (chip die IC LED)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/14 13:45
-	4	((("6051848") or ("6274890"))).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/14 13:47
-	2027	257/88,91,94-100.ccls. and (chip die LED IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/14 13:51
-	3	257/88,91,94-100.ccls. and (chip die LED IC) and ((amorphous adj fluororesin) PTFE)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/14 13:50
-	2027	257/88,91,94-100.ccls. and (chip die LED IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/14 13:52
-	284	257/88,91,94-100.ccls. and (chip die LED IC) and lead and resin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/14 16:00
-	2408	257/666,690,692-693,787-788,790.ccls. and (chip die LED IC) and lead and resin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/14 16:13
-	423	257/666,690,692-693,787-788,790.ccls. and (chip die LED IC) with coat\$4 and lead and resin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/14 16:51

-	1	(257/\$.ccls. 438/\$.ccls.) and (amorphous adj fluororesin) with (PTFE polytetrafluoroethylene)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/14 16:53
-	3	(amorphous adj fluororesin) with (PTFE polytetrafluoroethylene)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/16 15:04
-	2620	438/612-614,108,118.ccls. and (bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 14:05
-	170	438/612-614,108,118.ccls. and (bump ball) with (\$1m micrometer m)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 14:13
-	138	438/612-614,108,118.ccls. and (bump ball) with pitch and (\$1m micrometer m)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 14:28
-	205	438/612-614,108,118.ccls. and (bump ball) with (pitch spac\$4) and (\$1m micrometer m)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 14:16
-	1107	438/612-614,108,118.ccls. and (bump ball) with (layer adher\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 15:06
-	0	("59373210").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 14:34
-	2	("5937320").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 14:34
-	4	("5162257" "5391514" "5470787" "5634268").PN.	USPAT	2003/01/15 14:35
-	17	5937320.URPN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 14:35
-	502	257/733,778-779.ccls. and (bump ball) with (layer adher\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 15:08
-	73	257/733,778-779.ccls. and (bump ball) with (layer adher\$4) and (bond adj pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 15:08
-	667	(bump ball) with (layer adher\$4) and (bond adj pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 15:09
-	219	(bump ball) with pitch and (layer adher\$4) and (bond adj pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 15:09

-	3	(bump ball) with pitch with (layer adher\$4) and (bond adj pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 15:30
-	1372	adher\$4 with ((protective passivation) with (barrier metal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 15:32
-	281	adher\$4 with ((protective passivation) adj layer) with (barrier metal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 15:33
-	36	adher\$4 with ((protective passivation) adj layer) with (barrier metal) and (bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 16:46
-	2	("6465582").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/16 13:10
-	2	("6245259").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/16 15:04
-	0	257/290-294.ccls. and (coating adj film) near2 thickness with m	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/16 15:43
-	0	257/290-294.ccls. and (coating adj film) with thickness with (m micrometer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/16 15:44
-	41	(chip die IC LED) and (coating adj film) with thickness with (m micrometer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/16 20:14
-	11234	(chip die IC LED lead wire) and (coating adj film)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/16 15:53
-	1987	(chip die IC LED lead wire) with (coating adj film)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/16 15:54
-	1324	(lead wire) with (coating adj film)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/16 15:54
-	319	(lead wire) near2 (coating adj film)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/16 16:21
-	1	(lead wire) near2 (coating adj film) and (amorphous adj fluoro resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/16 16:02

-	17	(lead wire) and (amorphous adj fluororesin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/16 16:03
-	730	(lead wire) near2 ((coating adj film) (plating adj layer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/16 16:23
-	47	lead\$4 near4 wir\$4 near2 ((coating adj film) (plating adj layer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/16 16:28
-	405	lead\$4 and wir\$4 near5 ((coating adj film) (plating adj layer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/16 16:35
-	1	lead\$4 and wir\$4 near5 ((coating adj film) (plating adj layer)) and (amorphous adj fluororesin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/16 16:52
-	26	(coating adj (film layer)) near2 (micrometer um)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/21 13:12
-	2	("5221859").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/16 20:25